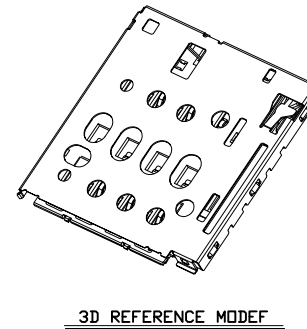
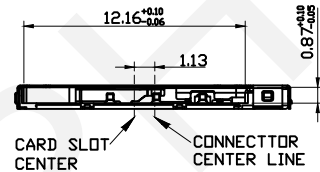
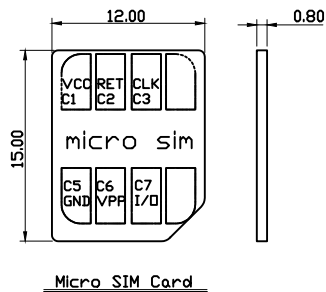
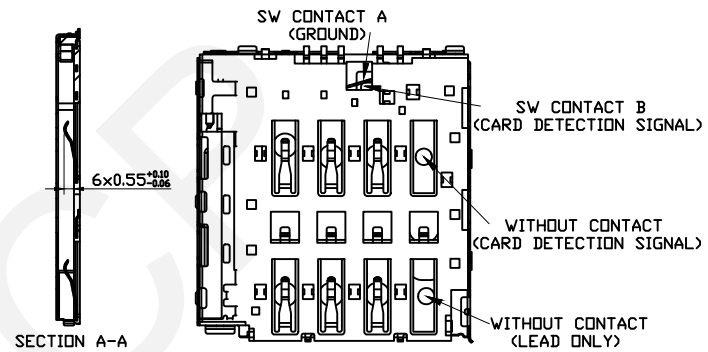
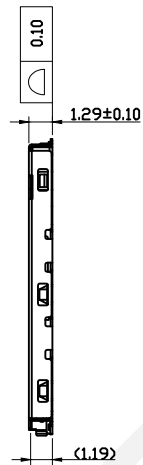
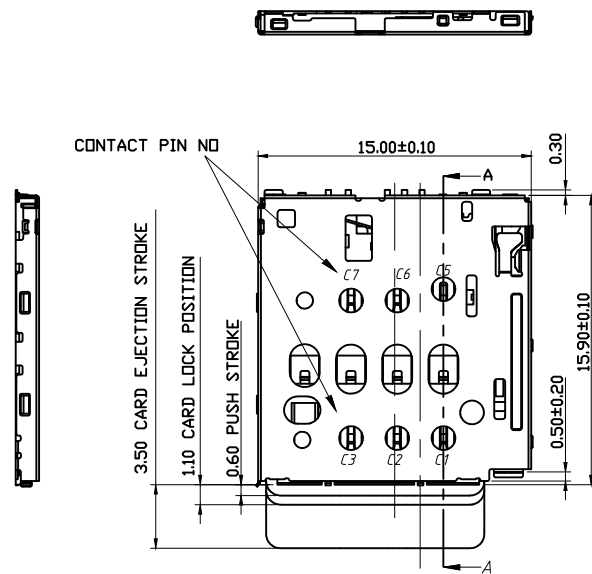
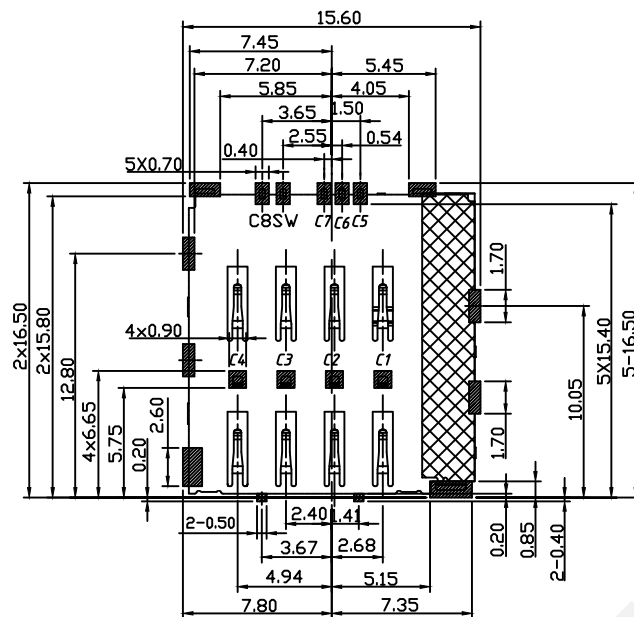




UNITS:mm	SHEET SIZE: A4		SCALE:---	DRWN BY PAN
0~3	3~18	18~50	50~120	CHK'D BY FENG
±0.12	±0.15	±0.3	±0.5	APPR BY ZHAN

Micro SIM CONN;PUSH/PUSH,8Pin, H1.29mm,with CD Pin	
THIRD ANGLE PROJECTION 	RHTAYIM-093-H1.29-R



■ CIRCUIT TRACE KEEP AREA
 ▨ SMT SOLDER AREA

RECOMMENDED PCB LAYOUT
 COMPONENT SIDE (TOLERANCE ±0.05)

Material:

Housing: High Temperature Thermoplastic, UL94V-0

Contact: Copper Alloy, Au 1u", Solder area: Gold Flash; Under plate Ni40u"

Min all over

Shell: SUS, Plated 30u" Ni Overall, Solder area: Gold Flash

Electrical:

Current Rating: 0.5A

Voltage Rating: 50V DC Max.

Contact Resistance: 100mΩ Max.

Dielectric Withstanding Voltage: 500V AC

Insulation Resistance: 1000MΩ Min./250VDC

Ambient Temperature Range: -20°C ~ +85°C Storage

Temperature Range: -40°C ~ +70°C Ambient Humidity Range: 95% R.H. Max.

Peak Temperature: 260°C ± 5°C

Mating Cycles: 5000 Insertions

SIM PIN Assignment

PIN NO	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

CARD INSERTION STATE	CARD DETECT SW
CARD UN-INSERTION	CLOSE
CARD INSERTION	OPEN